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ABSTRACT OF THE DISCLOSURE

5 An electrical multilayer component (1) is suggested which has a main body (5) constructed from stacked dielectric layers. Electrode areas, in which electrodes (10A, 15A) are realized, are arranged at intervals between the dielectric layers. These electrodes (10A, 15A) are contacted in an electrically conductive way by at least two bumps (10, 15) for the electrical contact of the component. A component of  
10 this type displays an especially high integration density of passive components and may be mounted especially simply on a substrate using flip chip construction.

Figure 5B